

ABSTRACT**THERMOSETTING RESIN COMPOSITION FOR SEMICONDUCTOR DEVICES ENCAPSULATION AND SEMICONDUCTOR DEVICES**

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The present invention provides a thermosetting resin composition for sealing of electronic parts, which has excellent storage stability at room temperature.

In an aspect of the present invention, there is provided a thermosetting resin composition used for sealing of semiconductor devices, comprising:

- 10 (e) an epoxy resin;
(f) a phenolic resin curing agent;
(g) an amine curing catalyst; and
(h) a compound having the formula $M-Z-R^1$, where M is a metal, Z is an oxygen or sulfur radical and R^1 is selected from the group consisting of hydrogen and C_1 to C_5 alkyl.

15 In another aspect of the present invention, there is provided a thermosetting resin composition.

In another aspect of the present invention, there is provided a semiconductor device encapsulated by the thermosetting resin composition of the present invention.